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JPW

Att. Docket No. 10191/1629

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Appl. Serial No. : 09/720,761 Confirmation No. 5642  
Title : METHOD OF PLASMA ETCHING OF SILICON  
Applicant(s) : Franz LAERMER et al.  
Filed : March 26, 2001  
TC/A.U. : 1765  
Examiner : Kin Chan Chen  
Docket No. : 10191/1629  
Customer No. : 26646

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Commissioner for Patents  
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Alexandria, VA 22313-1450

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Date: 5/13/2004

Signature: [Signature]

**AARON C. DEDITCH**  
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**TRANSMITTAL OF REPLACEMENT AMENDMENT**

SIR:

Transmitted herewith for filing in the above-identified patent application is a Replacement Amendment for the Amendment filed March 31, 2004 (and mailed on March 29, 2004).

While no fee is believed to be due (since this Replacement Amendment is being filed within one month of the Notice of Non-Compliant Amendment mailed on April 13, 2004), the Commissioner is authorized to charge payment of any fees (including any extension fees) associated with this communication or credit any overpayment to the deposit account of **Kenyon & Kenyon**, deposit account number **11-0600**. A duplicate copy of this page is enclosed.

Respectfully submitted,

Dated: 5/13/2004

By: [Signature]

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